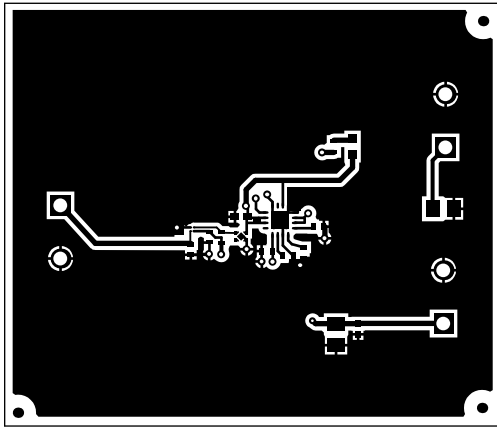
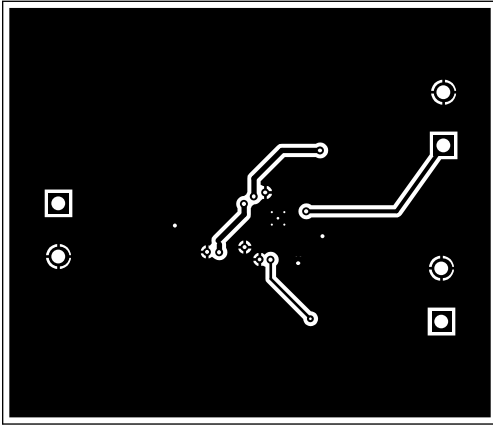


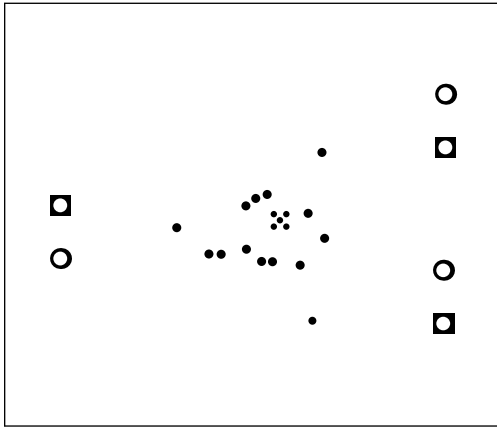
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00600	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00600		
PLOT NAME = Top Solder Mask	GENERATED : 9/4/2015 4:36:50 PM	TEXAS INSTRUMENTS	



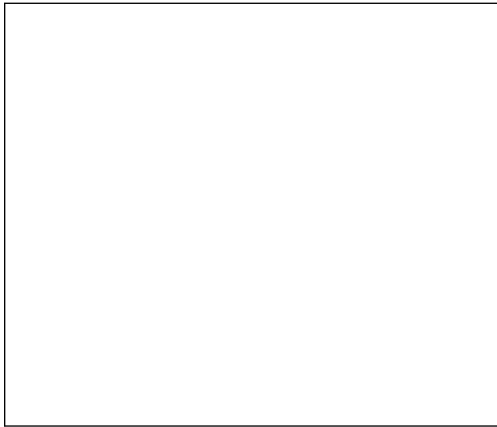
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00600	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00600		
PLOT NAME = Top Layer	GENERATED : 9/4/2015	4:36:51 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00600	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00600		
PLOT NAME = Bottom Layer	GENERATED : 9/4/2015 4:36:51 PM	TEXAS INSTRUMENTS	

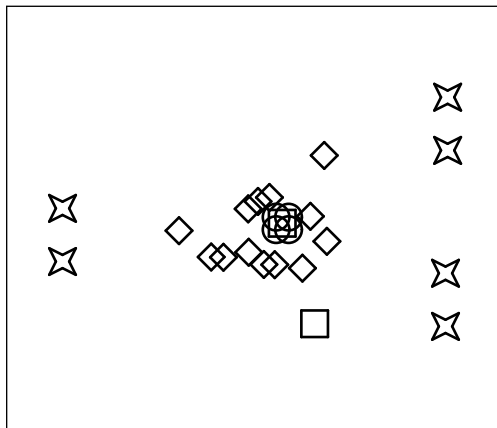


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00600	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-00600		
PLOT NAME = Bottom Solder Mask	GENERATED : 9/4/2015 4:36:52 PM	TEXAS INSTRUMENTS	

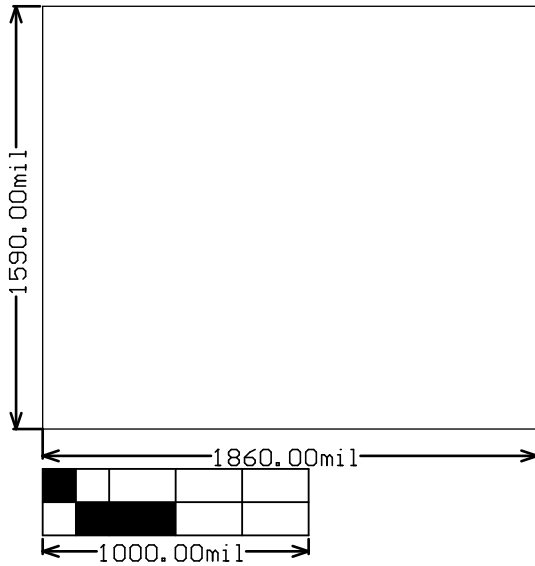


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00600	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00600		
PLOT NAME = Bottom Overlay	GENERATED : 9/4/2015	4:36:52 PM	TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
○	4	7.87mil (0.200mm)	PTH	Round
□	2	10.00mil (0.254mm)	PTH	Round
◇	13	15.00mil (0.381mm)	PTH	Round
✕	6	51.18mil (1.300mm)	PTH	Round
25 Total				



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00600	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00600		
PLOT NAME = Drill Drawing	GENERATED : 9/4/2015	4:36:53 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00600	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-00600		
PLOT NAME = Board Dimensions	GENERATED : 9/4/2015	4:36:54 PM	TEXAS INSTRUMENTS

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